

Description

The CL9703 is a 1.0uA supply current and fast response low dropout voltage regulator which designed for applications requiring low quiescent current, low dropout voltage and high power supply ripple rejection. It guarantees delivery of 300mA output current, and supports preset output voltage versions range include 1.1V, 1.2V, 1.3V, 1.5V, 1.7V, 1.8V, 1.9V, 2.0V, 2.3V, 2.5V, 2.6V, 2.7V, 2.8V, 2.9V, 3.0V, 3.3V, 3.6V.

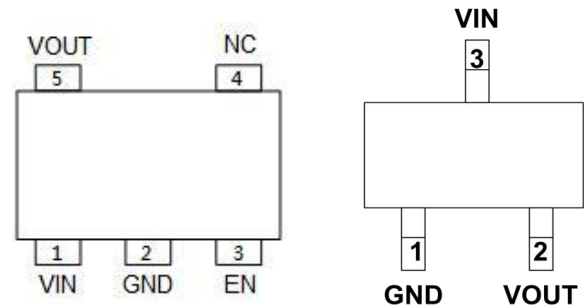
The CL9703 features a precise $\pm 2\%$ output regulation over load and line variations, also the CL9703 integrates many functions. The function of thermal shutdown and over current limit protect the device against thermal and current over-loads. Based on its low quiescent current consumption and its less than 0.1uA (typical) shutdown mode current, Besides with high power supply rejection ratio make the device holds well for low input voltages typically encountered in battery operation systems. The regulator is stable with small ceramic capacitor (typical 1.0uF).

Feature

- ◆ Input Voltage Range: 2.3V~5.5V
- ◆ Low Quiescent Current: 1.0uA (Typical)
- ◆ Low Dropout Voltage: 380mV@300mA
- ◆ $\pm 2\%$ Initial voltage reference accuracy
- ◆ Output Current Typical: 300mA
- ◆ Low Shutdown Current: 0.1uA
- ◆ High Power Supply Rejection Rate 78dB at 1KHz
- ◆ Fast Transient Response Over Line and Load Transient
- ◆ Built In Internal Soft Start
- ◆ Over Current Protection and Short-circuit Protection
- ◆ Over-temperature Protection
- ◆ Stable with 1 μ F minimum ceramic output capacitor
- ◆ SOT-23-5L
- ◆ Green Product RoHS Compliant and Halogen Free

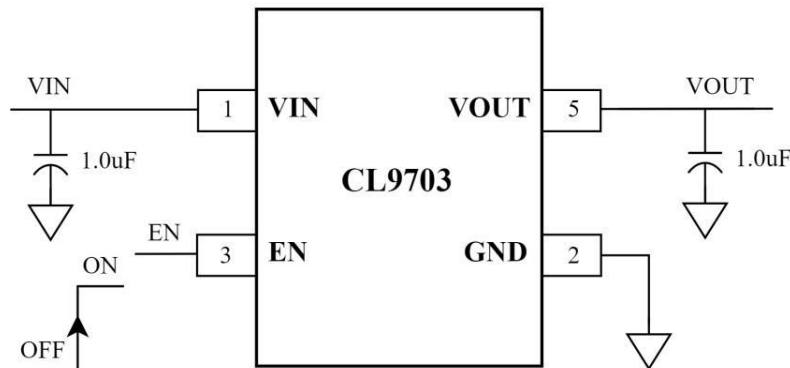
Applications

- ◆ Smart Phones and Tablets
- ◆ Portable&Battery-Powered Applications
- ◆ Ultra Low Power Micro-Controller
- ◆ Real Time Clock Backup Power
- ◆ Micro-Controller Power Supply
- ◆ Electronic sensors

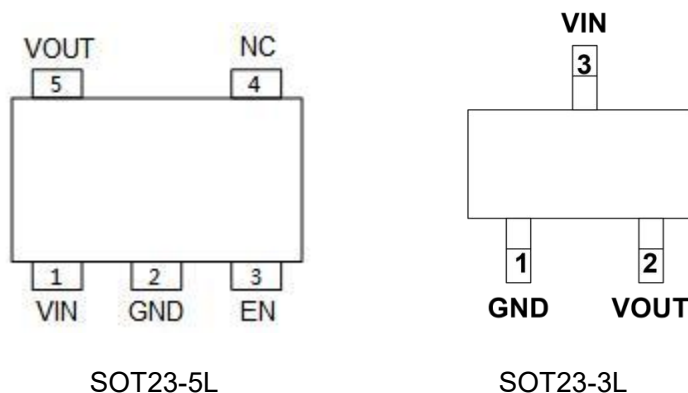


Package Type : SOT23-3L / SOT23-5L

Application Circuit

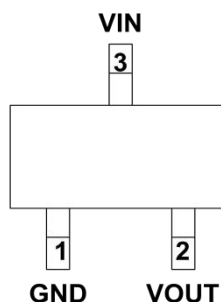


Pin Description

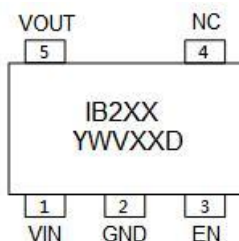


NO		NAME	DESCRIPTION
SOT23-3L	SOT23-5L		
3	1	VIN	Power supply voltage input. A 1.0uF ceramic capacitor is recommended at this pin.
1	2	GND	IC Ground.
	3	EN	EN: Pulling this pin to high/low will enable/disable the device. EN Floating is not recommend allowed.
	4	NC	Not connected.
2	5	VOUT	Regulated Output Voltage. The power output of the device. A 1.0uF ceramic capacitor is recommended at this pin.

Marking Information



As shown in the left figure:
First row:
IB1: Model code
XX: Output voltage (33: VOUT=3.3V)



As shown in the left figure:
First row:
IB2: Model code
XX: Output voltage (33: VOUT=3.3V)
Second row:
Y: Age code
W: Week Code
VXX: Batch code
D: Environmental code

PART NUMBER	PACKAGE TYPE	MARKING
CL9703A12L3M	SOT23-3L	IB112
CL9703A15L3M	SOT23-3L	IB115
CL9703A18L3M	SOT23-3L	IB118
CL9703A28L3M	SOT23-3L	IB128
CL9703A30L3M	SOT23-3L	IB130
CL9703A33L3M	SOT23-3L	IB133
CL9703A12L5M	SOT23-5L	IB212
CL9703A15L5M	SOT23-5L	IB215
CL9703A18L5M	SOT23-5L	IB218
CL9703A25L5M	SOT23-5L	IB225
CL9703A28L5M	SOT23-5L	IB228
CL9703A30L5M	SOT23-5L	IB230
CL9703A33L5M	SOT23-5L	IB233

Absolute Maximum Ratings (note 1)

SYMBOL	PARAMETER	LIMIT	UNIT
V _{IN}	Power Supply Operation Voltage	-0.3<V _{IN} <6	V
V _{OUT}	Output Voltage	-0.3V<V _{OUT} <V _{IN} +0.3	V
V _{EN}	Enable Input Voltage	-0.3<V _{IN} <6	V
I _{OUT}	Output Operation Current	300	mA
P _{D_SOT23}	Package Power Dissipation at T _A ≤ 25°C	420	mW
T _J	Junction Temperature	-40~150	°C
T _{STG}	Storage Temperature	-65~150	°C
T _{LEAD}	Lead Temperature Soldering Time	260(10S)	°C
V _{ESD_HBM}	ESD (Human Body Mode) (Note 2)	2K	V
V _{ESD_MM}	ESD (Machine Mode) (Note 2)	200	V

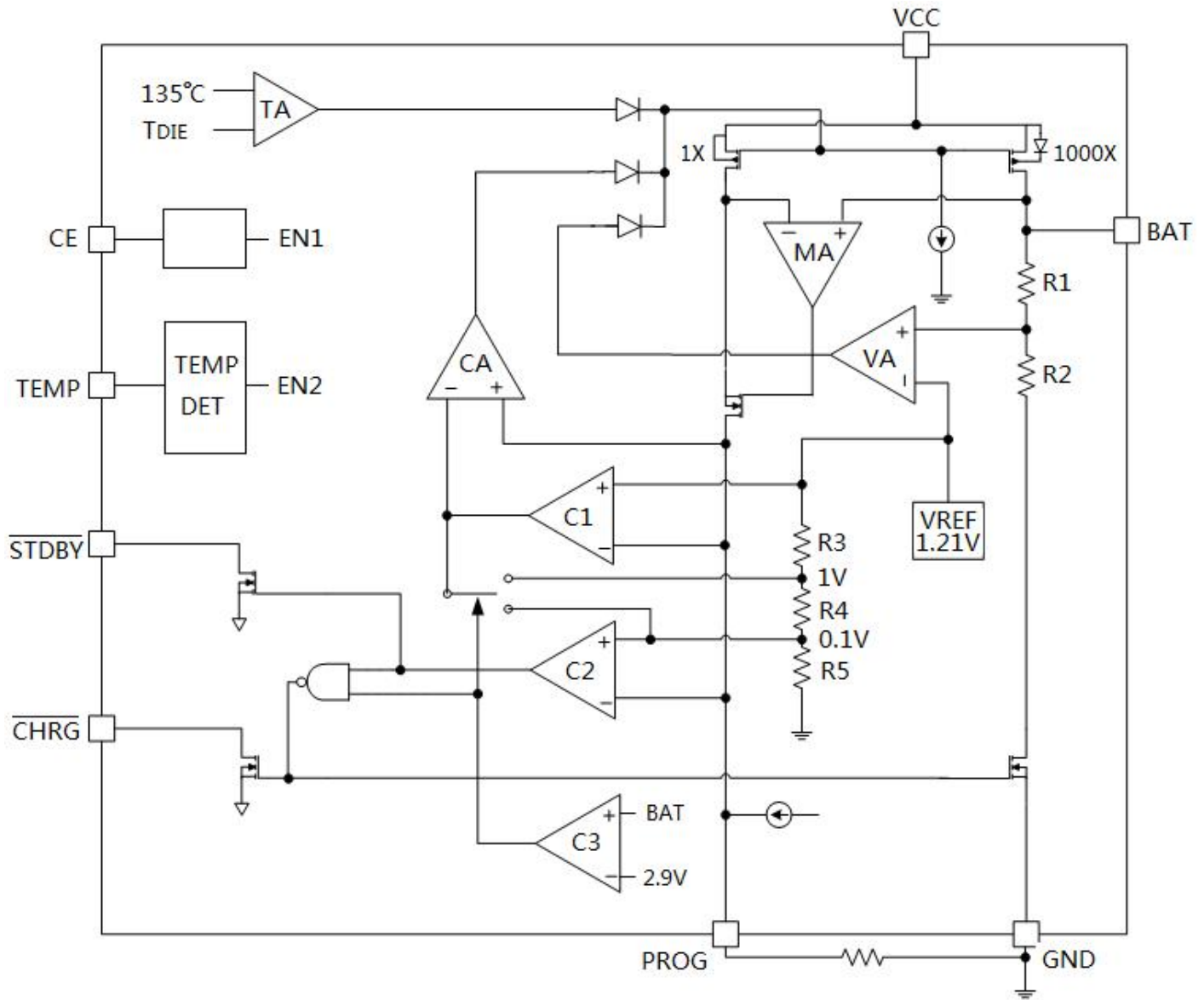
Thermal Information (Note 3)

SYMBOL	PARAMETER	LIMIT	UNIT
θ _{JA_SOT23-5}	Thermal Resistance Junction to Ambient	238	°C/W

Recommended Operating Condition (Note 4)

SYMBOL	PARAMETER	LIMIT	UNIT
V _{IN}	Power Supply Operation Voltage	2.3 to 5.5	V
T _J	Junction Temperature	-40~125	°C
T _A	Operating Temperature Range	-40~85	°C

Functional Block Diagram



Functional Block Diagram

Electrical Characteristics

($V_{IN}=V_{OUT}(\text{NOM})+1\text{V}$ or 2.3V (Whichever is greater) $C_{IN}=1.0\mu\text{F}$, $C_{OUT}=1.0\mu\text{F}$, $T_A = 25^\circ\text{C}$ for typical specifications, unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Supply Voltage Section						
V _{IN}	VIN Operation Voltage Range	VIN Input Range	2.3		5.5	V
V _{OUT}	VOUT Output Regulated Voltage	VOUT Output Range	1.1		3.6	V
I _{VIN}	VIN Supply Current	VIN=EN=5V, Unload		1.0		uA
I _{SHDN}	Input Current At IC Shutdown	VIN=5V, EN=0V		0.1	1.0	uA
I _{OUT}	Output Current (Note 5)	Normal Operation Output Current	300			mA
Enable						
V _{ENH}	EN Input Voltage High	VIN=5V, IOUT=1mA	1.2			V
V _{ENL}	EN Input Voltage Low	VIN=5V, IOUT=1mA			0.3	V
Output Voltage Section						
V _{OUT}	Output Voltage Accuracy	IOUT=1mA	-2.0		+2.0	%
△V _{LNR}	Line Regulation For VIN	VIN=(VOUT+1V, 2.3V) to 5.5V IOUT=1mA		0.5		%/V
△V _{LDR}	Load Regulation For VOUT	VIN=VOUT+1V IOUT=1mA to 100mA		12.0		mV
RDischg	Auto-Discharge Resistance	VIN=5V, VEN=0V		2.3		KΩ
V _{DROP}	Dropout Voltage (Note 6)	VOUT=3.3V, IOUT=300mA		380		mV
		VOUT=3.3V, IOUT=150mA		190		mV
PSRR						
PSRR	Power Supple Ripple Rejection Rate	VIN=Max{VOUT+1.0V,2.3V}, F=1KHz, Ripple=0.2Vpp, IOUT=50mA		78.0		dB
		VIN=Max{VOUT+1.0V,2.3V}, F=10KHz, Ripple=0.2Vpp, IOUT=50mA		40.0		dB
Over Current Protection						
I _{LIM}	Limit Current	VIN=VEN=5V	350			mA
I _{SHORT}	Short Current	VOUT < 0.2V		500		mA
Thermal Shutdown						
T _{SD}	Thermal Shutdown Temperature	TJ Rising		150		℃
	Thermal Shutdown Returned Temperature			130		℃

Note 1. Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Note 2. Devices are ESD sensitive. Handling precaution recommended.

Note 3. θ_{JA} is measured in the natural convection at $T_A=25^\circ\text{C}$ on a high effective thermal conductivity test board of JEDEC 51-7 thermal measurement standard.

Note 4. The device is not guaranteed to function outside its operating conditions.

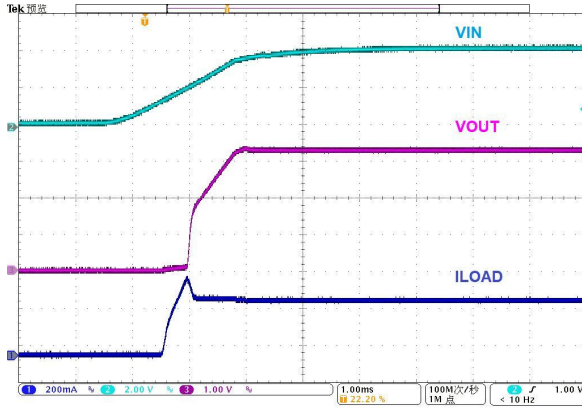
Note 5. The output current at which the output voltage becomes 95% of VOUT after gradually increasing the output current. Also The output current can be at least this value. Due to restrictions on the package power dissipation, this value may not be satisfied. Attention should be paid to the power dissipation of the package when the output current is large. The specification is guaranteed by design.

Note 6. The dropout voltage is defined as $V_{IN} - V_{OUT}$, which is measured when VOUT is 98%*VOUT.

Typical Performance Characteristics

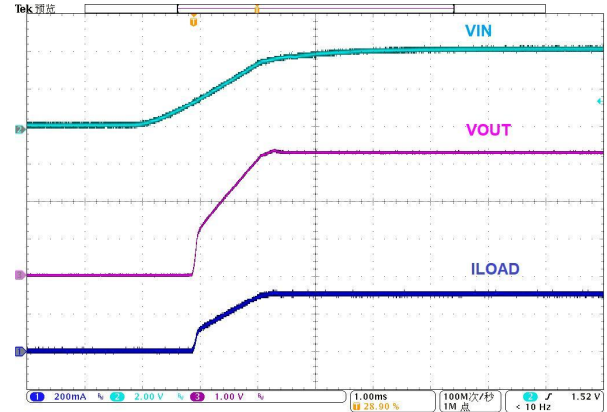
($T_A = 25^\circ\text{C}$, $C_{IN}=1\mu\text{F}$, $C_{OUT}=1\mu\text{F}$, unless otherwise specified)

Power On from VIN With 300mA LOAD



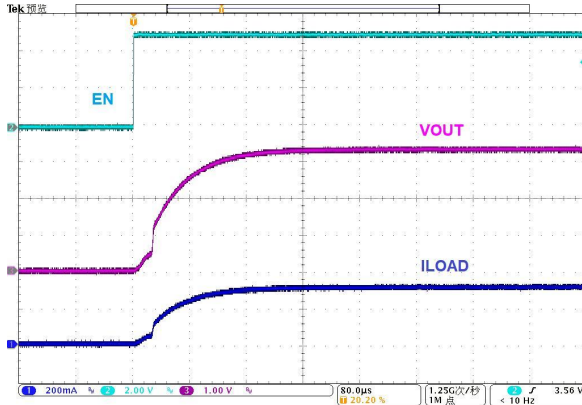
VIN=4.3V, VOUT=3.3V, ILOAD=300mA

Power On from VIN With 11ohm LOAD



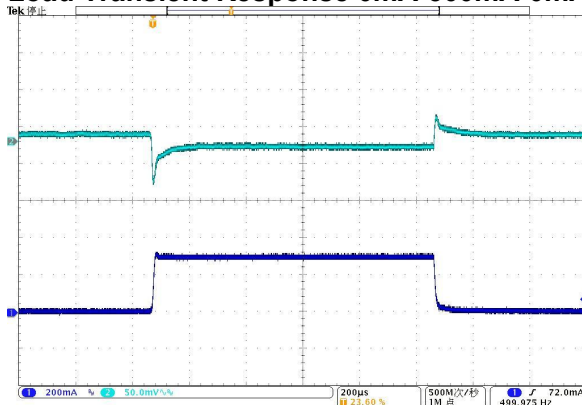
EN=5.0V, VIN=4.3V, VOUT=3.3V, RLOAD=11ohm

Power On from EN With 11ohm LOAD



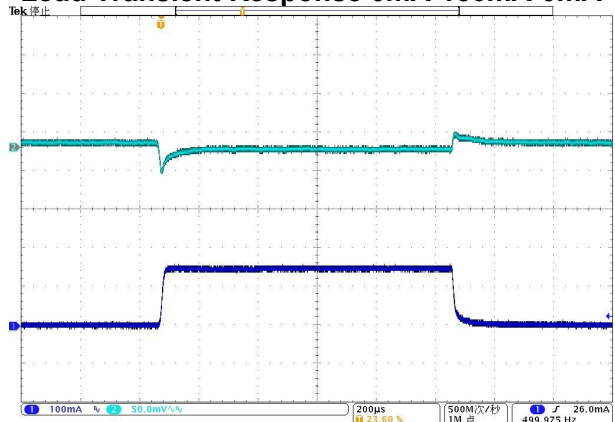
VIN=4.3V, VOUT=3.3V, RLOAD=11ohm

Load Transient Response 0mA-300mA-0mA

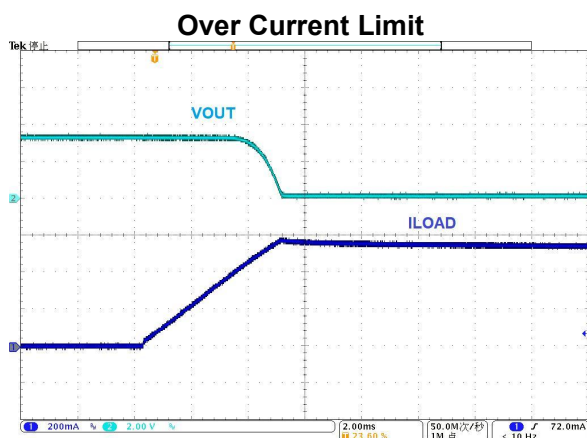


VIN=4.3V, VOUT=3.3V, ILOAD=0mA-300mA-0mA

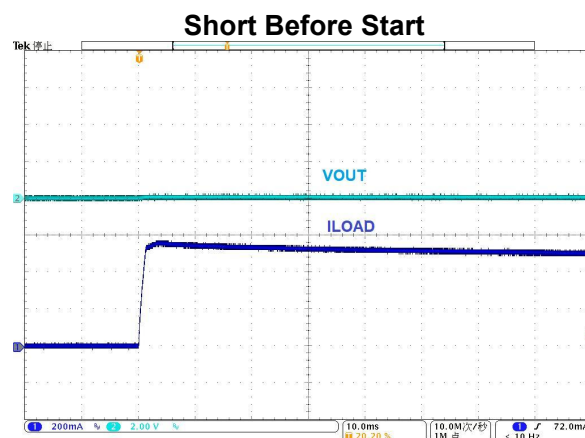
Load Transient Response 0mA-150mA-0mA



VIN=4.3V, VOUT=3.3V, ILOAD=0mA-150mA-0mA

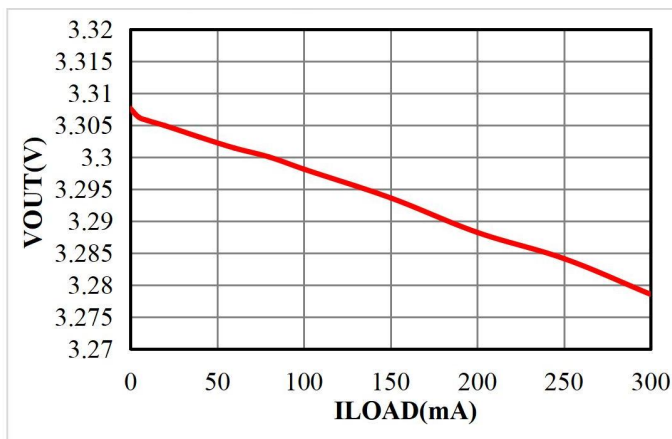


VIN=4.3V, VOUT=3.3V



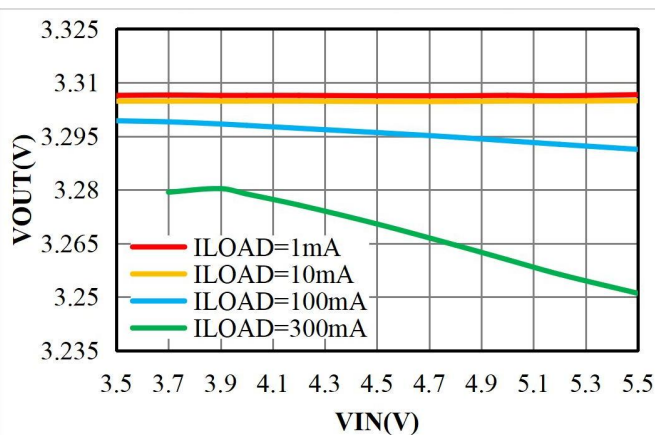
VIN=4.3V, VOUT=0V

Output Voltage vs. Load Current



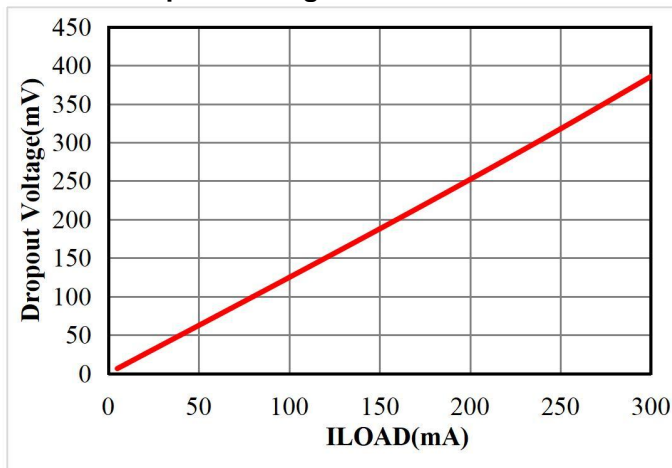
VIN=4.3V, VOUT=3.3V, ILOAD=0mA-300mA

Output Voltage vs. Input Voltage



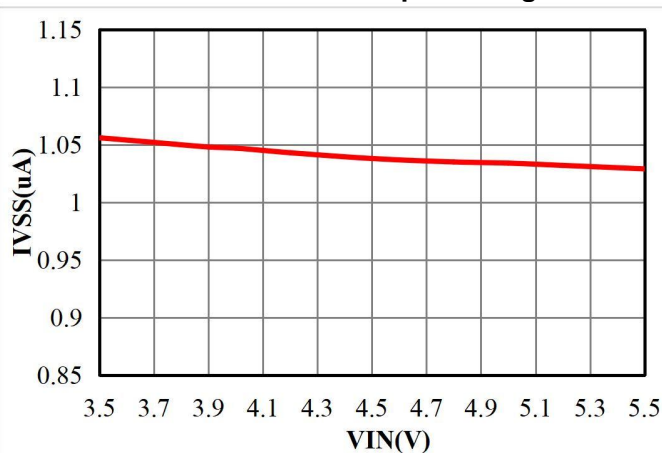
VIN=3.5-5.5V, VOUT=3.3V, ILOAD=1mA-300mA

Dropout Voltage vs. Load Current



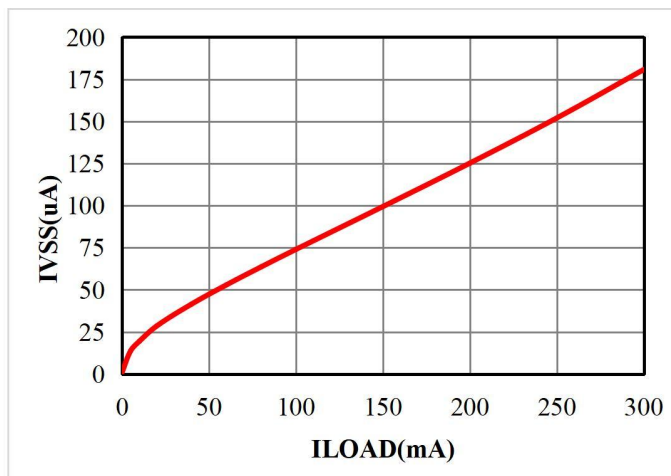
VOUT=3.3V, ILOAD=0mA-300mA

Ground Current vs. Input Voltage



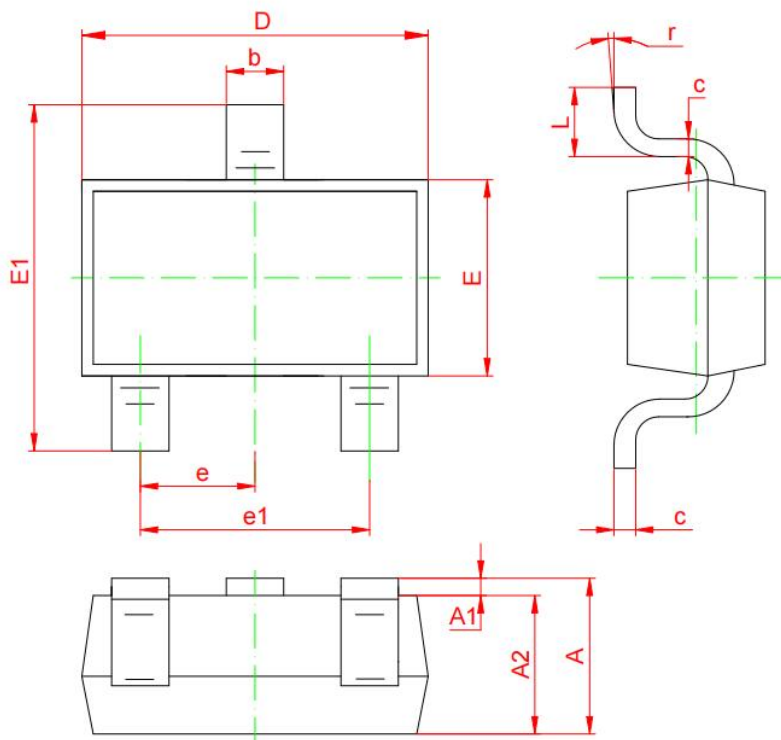
VIN=3.5-5.5V, VOUT=3.3V, ILOAD=0mA

Ground Current vs. Load Current



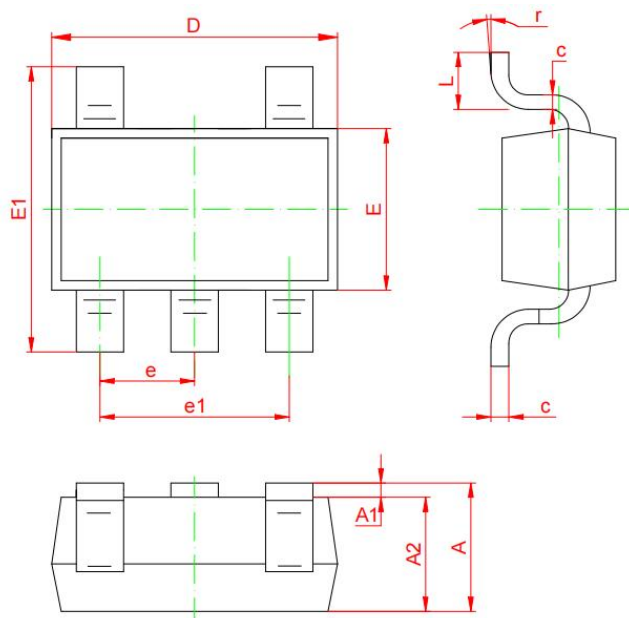
VIN=4.3V, VOUT=3.3V, ILOAD=0-300mA

Package Outline: SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 (BSC)		0.037 (BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
r	0°	8°	0°	8°

Package Outline: SOT-23-5L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 (BSC)		0.037 (BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
r	0°	8°	0°	8°

- The information described herein is subject to change without notice.
- CHIPLINK Technology is not responsible for any problems caused by circuits or diagrams described herein whose related industrial properties, patents, or other rights belong to third parties. The application circuit examples explain typical applications of the products, and do not guarantee the success of any specific mass-production design.
- When the products described herein are regulated products subject to the Wassenaar Arrangement or other agreements, they may not be exported without authorization from the appropriate governmental authority.
- Use of the information described herein for other purposes and/or reproduction or copying without the express permission of CHIPLINK Technology is strictly prohibited.
- The products described herein cannot be used as part of any device or equipment affecting the human body, such as exercise equipment, medical equipment, security systems, gas equipment, or any apparatus installed in airplanes and other vehicles, without prior written permission of CHIPLINK Technology.
- Although CHIPLINK Technology exerts the greatest possible effort to ensure high quality and reliability, the failure or malfunction of semiconductor products may occur. The user of these products should therefore give thorough consideration to safety design, including redundancy, fire-prevention measures, and malfunction prevention, to prevent any accidents, fires, or community damage that may ensue.